



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR TSSOP-8					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
HAST	250	25 000	130 °C, 85 % RH	0	0
Pressure Pot	500	48 000	121°, 15 PSIG	0	0
Solder DUNK	60	180	260 °C, 10 s	0	0
Temp. Cycle	1500	600 000	-55 °C to 150 °C	0	0